2SJ575

Silicon P Channel MOS FET High Speed Switching

HITACHI

ADE-208-740B (Z) 3rd.Edition. June 1999

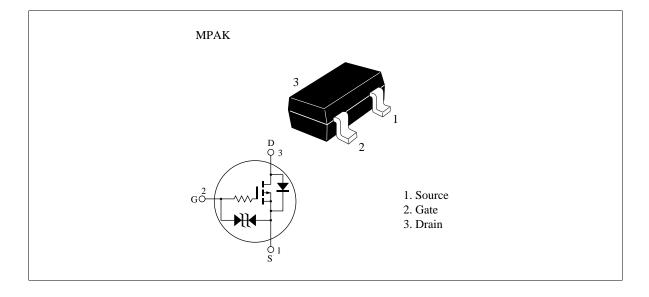
Features

Low on-resistance

$$\begin{split} R_{DS} = & 2.8 & \text{typ. (V} \quad_{GS} = -10 \text{ V} \text{ , I}_{D} = -50 \text{ mA}) \\ R_{DS} = & 5.7 & \text{typ. (V} \quad_{GS} = -4 \text{ V} \text{ , I}_{D} = -50 \text{ mA}) \end{split}$$

- 4 V gate drive device.
- Small package (MPAK)

Outline





2SJ575

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	Ratings	Unit
Drain to source voltage	$V_{ exttt{DSS}}$	-30	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	-100	mA
Drain peak current	Note1 D(pulse)	-400	mA
Body-drain diode reverse drain current	I _{DR}	-100	mA
Channel dissipation	Pch Note 2	400	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note:

1. PW 10 µs, duty cycle 1%

2. Value on the alumina ceramic board (12.5x20x0.7mm)

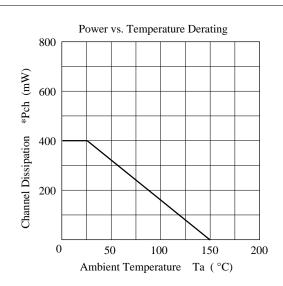
Electrical Characteristics ($Ta = 25^{\circ}C$)

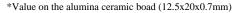
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-30	_	_	V	$I_D = -100 \ \mu A, \ V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±5	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltege drain current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -30 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-1.3	_	-2.3	V	$I_D = -10\mu A, V_{DS} = -5 V$
Static drain to source on state	R _{DS(on)}	_	2.8	3.3		$I_D = -50 \text{ mA}, V_{GS} = -10 \text{ V}^{\text{Note 3}}$
resistance	R _{DS(on)}	_	5.7	7.9		$I_D = -50 \text{ mA}, V_{GS} = -4 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	68	105	_	mS	$I_D = -50 \text{ mA}, V_{DS} = -10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	25	_	pF	V _{DS} = -10 V
Output capacitance	Coss	_	20	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	8	_	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	_	10	_	ns	$I_D = -50 \text{mA}, V_{GS} = -10 \text{ V}$
Rise time	t _r	_	15	_	ns	R _L = 200
Turn-off delay time	t _{d(off)}	_	40	_	ns	
Fall time	t _f	_	45	_	ns	

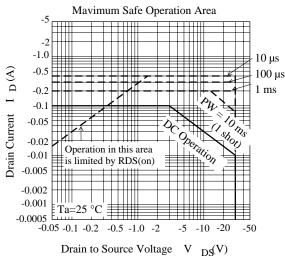
Note: 3. Pulse test

4. Marking is AP

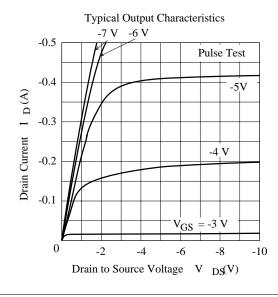
Main Characteristics

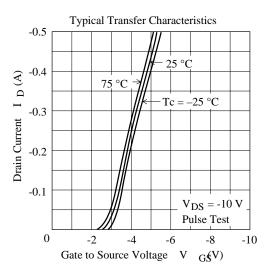


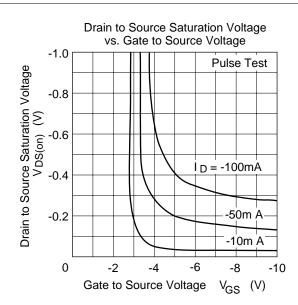


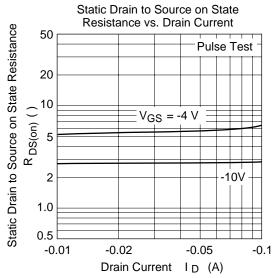


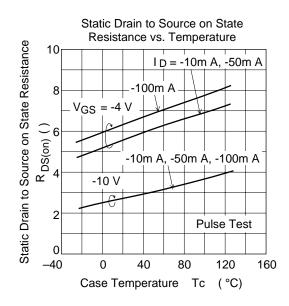
Value on the alumina ceramic boad (12.5x20x0.7mm)

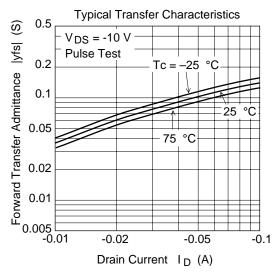


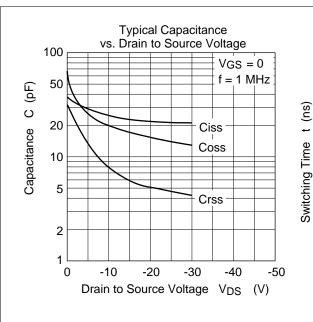


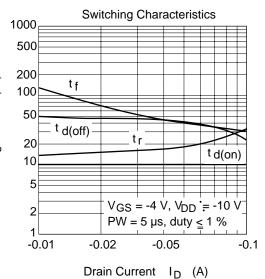


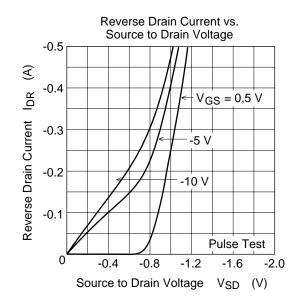


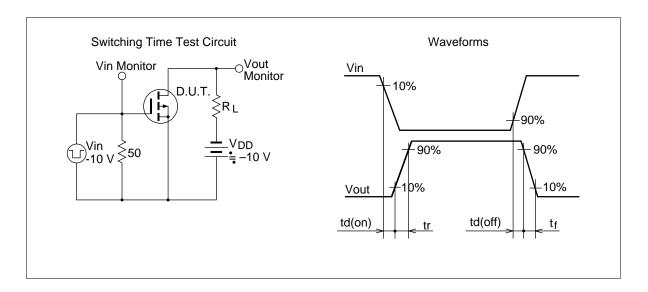




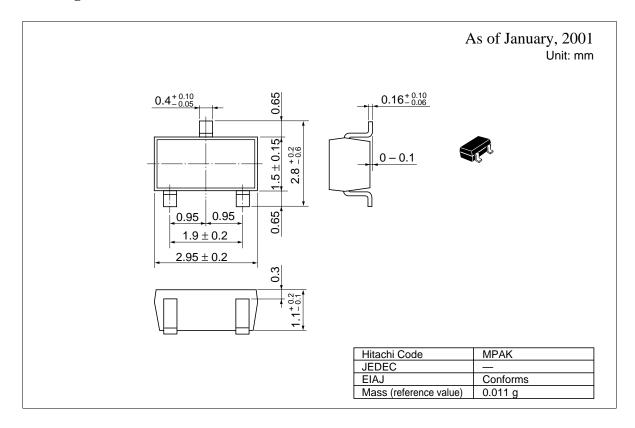








Package Dimensions



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Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

NorthAmerica : http://semiconductor.hitachi.com/ Europe http://www.hitachi-eu.com/hel/ecg Asia http://sicapac.hitachi-asia.com Japan http://www.hitachi.co.jp/Sicd/indx.htm

For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose,CA 95134 Tel: <1> (408) 433-1990 Germany

Hitachi Europe GmbH Electronic Components Group Dornacher Straße 3 D-85622 Feldkirchen, Munich Fax: <1>(408) 433-0223 Tel: <49> (89) 9 9180-0 Fax: <49> (89) 9 29 30 00

> Hitachi Europe Ltd. Electronic Components Group. Whitebrook Park Lower Cookham Road Maidenhead Berkshire SL6 8YA, United Kingdom Tel: <886>-(2)-2718-3666 Tel: <44> (1628) 585000 Fax: <44> (1628) 585160

Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel: <65>-538-6533/538-8577

Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg

Hitachi Asia Ltd (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building.

Taipei (105), Taiwan Fax: <886>-(2)-2718-8180 Telex: 23222 HAS-TP URL: http://www.hitachi.com.tw Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong

Tel: <852>-(2)-735-9218 Fax: <852>-(2)-730-0281 URL: http://www.hitachi.com.hk

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